



# dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A

## dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A Family Silicon Errata and Data Sheet Clarification

The dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A family devices that you have received conform functionally to the current Device Data Sheet (DS70593B), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in [Table 1](#). The silicon issues are summarized in [Table 2](#).

The errata described in this document will be addressed in future revisions of the dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A silicon.

**Note:** This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of [Table 2](#) apply to the current silicon revision (**A4**).

Data Sheet clarifications and corrections start on page 8, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB® IDE and Microchip's programmers, debuggers and emulation tools, which are available at the Microchip corporate web site ([www.microchip.com](http://www.microchip.com)).

For example, to identify the silicon revision level using MPLAB IDE in conjunction with MPLAB ICD 2 or PICKit™ 3:

1. Using the appropriate interface, connect the device to the MPLAB ICD 2 programmer/debugger or PICKit 3.
2. From the main menu in MPLAB IDE, select *Configure>Select Device*, and then select the target part number in the dialog box.
3. Select the MPLAB hardware tool (*Debugger>Select Tool*).
4. Perform a "Connect" operation to the device (*Debugger>Connect*). Depending on the development tool used, the part number *and* Device Revision ID value appear in the **Output** window.

**Note:** If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The Device and Revision ID values for the various dsPIC33FJ64GPX06A/X08A/X10A and dsPIC33FJ128GPX06A/X08A/X10A silicon revisions are shown in [Table 1](#).

**TABLE 1: SILICON DEVREV VALUES**

Part Number	Device ID <sup>(1)</sup>	Revision ID for Silicon Revision <sup>(2)</sup>	
		A3	A4
dsPIC33FJ64GP206A	0x00C1	0x3009	0x300A
dsPIC33FJ64GP306A	0x00CD		
dsPIC33FJ64GP310A	0x00CF		
dsPIC33FJ64GP706A	0x00D5		
dsPIC33FJ64GP708A	0x00D6		
dsPIC33FJ64GP710A	0x00D7		
dsPIC33FJ128GP206A	0x00D9		
dsPIC33FJ128GP306A	0x00E5		
dsPIC33FJ128GP310A	0x00E7		

**Note 1:** The Device and Revision IDs (DEVID and DEVREV) are located at the last two implemented addresses in program memory.

**2:** Refer to the "dsPIC33F/PIC24H Flash Programming Specification" (DS70152) for detailed information on Device and Revision IDs for your specific device.

**TABLE 1: SILICON DEVREV VALUES (CONTINUED)**

Part Number	Device ID <sup>(1)</sup>	Revision ID for Silicon Revision <sup>(2)</sup>	
		A3	A4
dsPIC33FJ128GP706A	0x00ED	0x3009	0x300A
dsPIC33FJ128GP708A	0x00EE		
dsPIC33FJ128GP710A	0x00EF		

- Note 1:** The Device and Revision IDs (DEVID and DEVREV) are located at the last two implemented addresses in program memory.
- 2:** Refer to the “dsPIC33F/PIC24H Flash Programming Specification” (DS70152) for detailed information on Device and Revision IDs for your specific device.

**TABLE 2: SILICON ISSUE SUMMARY**

Module	Feature	Item Number	Issue Summary	Affected Revisions <sup>(1)</sup>	
				A3	A4
ECAN	Sleep Mode	1.	The WAKIF bit in the CxINTF register cannot be cleared by software instruction after the device is interrupted from Sleep due to activity on the CAN bus.	X	X
UART	IR Mode	2.	The 16x baud clock signal on the BCLK pin is present only when the module is transmitting.	X	X
UART	High-Speed Mode	3.	When the UART is in 4x mode (BRGH = 1) and using two Stop bits (STSEL = 1), it may sample the first Stop bit instead of the second one.	X	X
UART	Interrupts	4.	The UART error interrupt may not occur, or may occur at an incorrect time, if multiple errors occur during a short period of time.	X	X
I <sup>2</sup> C™	10-bit Addressing Mode	5.	When the I <sup>2</sup> C module is configured for 10-bit addressing using the same address bits (A10 and A9) as other I <sup>2</sup> C devices, the A10 and A9 bits may not work as expected.	X	X
I <sup>2</sup> C	—	6.	After the ACKSTAT bit is set when receiving a NACK, it may be cleared by the reception of a Start or Stop bit.	X	X
I <sup>2</sup> C	10-bit Addressing Mode	7.	The 10-bit slave does not set the RBF flag or load the I2CxRCV register on address match if the Least Significant bits (LSbs) of the address are the same as the 7-bit reserved addresses.	X	X
I <sup>2</sup> C	10-bit Addressing Mode	8.	When the I <sup>2</sup> C module is configured as a 10-bit slave with an address of 0x102, the I2CxRCV register content for the lower address byte is 0x01 rather than 0x02.	X	X
SPI	Frame Mode	9.	In framed SPI mode, when the FRMDLY bit (SPIxCON2<1>) is cleared and SMP bit (SPIxCON1<9>) is cleared, frame sync pulses do not get generated.	X	X
Internal Voltage Regulator	IPD	10.	When the VREGS bit (RCON<8>) is set to a logic '0', device may Reset and higher sleep current may be observed.	X	X
PSV Operations	—	11.	An address error trap occurs in certain addressing modes when accessing the first four bytes of any PSV page.	X	X
CPU	EXCH Instruction	12.	The EXCH instruction does not execute correctly.	X	X
SPI	Transmit Operation	13.	Writing to the SPIxBUF register as soon as TBF bit is cleared will cause SPI module to ignore written data.	X	X

- Note 1:** Only those issues indicated in the last column apply to the current silicon revision.

**TABLE 2: SILICON ISSUE SUMMARY (CONTINUED)**

Module	Feature	Item Number	Issue Summary	Affected Revisions <sup>(1)</sup>	
				A3	A4
ECAN	Transmission Queuing	14.	ECAN module may not transmit Buffer 0 data if Buffer 1 data is queued for transmission first.	X	X
UART	Break Character Generation	15.	The UART module will not generate back-to-back Break characters.	X	X
I/O	SDO1 Pin	16.	SDO1 pin may toggle while device is being programmed via PGECx/PGEDx pin pairs.	X	X
ADC	Current Consumption in Sleep Mode	17.	If the ADC module is in an enabled state when the device enters Sleep Mode, the power-down current (IPD) of the device may exceed the device data sheet specifications.	X	X
All	150°C Operation	18.	These revisions of silicon only support 140°C operation instead of 150°C for Hi-Temp operating temperature.	X	X

**Note 1:** Only those issues indicated in the last column apply to the current silicon revision.

## Silicon Errata Issues

**Note:** This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (**A4**).

### 1. Module: ECAN

The WAKIF bit in the CxINTF register cannot be cleared by software instruction after the device is interrupted from Sleep due to activity on the CAN bus.

When the device wakes up from Sleep due to CAN bus activity, the ECAN module is placed in operational mode. The ECAN Event interrupt occurs due to the WAKIF flag. Trying to clear the flag in the Interrupt Service Routine (ISR) may not clear the flag. The WAKIF bit being set will not cause repetitive Interrupt Service Routine execution.

#### Work around

Although the WAKIF bit does not clear, the device Sleep and ECAN Wake function continue to work as expected. If the ECAN event is enabled, the CPU will enter the Interrupt Service Routine due to the WAKIF flag getting set. The application can maintain a secondary flag, which tracks the device Sleep and Wake events.

#### Affected Silicon Revisions

A3	A4						
X	X						

### 2. Module: UART

When the UART is configured for IR interface operations (UxMODE<9:8> = 11), the 16x baud clock signal on the BCLK pin is present only when the module is transmitting. The pin is idle at all other times.

#### Work around

Configure one of the output compare modules to generate the required baud clock signal when the UART is receiving data or in an Idle state.

#### Affected Silicon Revisions

A3	A4						
X	X						

### 3. Module: UART

When the UART is in 4x mode (BRGH = 1) and using two Stop bits (STSEL = 1), it may sample the first Stop bit instead of the second one.

This issue does not affect the other UART configurations.

#### Work around

Use the 16x baud rate option (BRGH = 0) and adjust the baud rate accordingly.

#### Affected Silicon Revisions

A3	A4						
X	X						

### 4. Module: UART

The UART error interrupt may not occur, or may occur at an incorrect time, if multiple errors occur during a short period of time.

#### Work around

Read the error flags in the UxSTA register whenever a byte is received to verify the error status. In most cases, these bits will be correct, even if the UART error interrupt fails to occur.

#### Affected Silicon Revisions

A3	A4						
X	X						

### 5. Module: I<sup>2</sup>C

If there are two I<sup>2</sup>C devices on the bus, one of them is acting as the Master receiver and the other as the Slave transmitter. If both devices are configured for 10-bit addressing mode, and have the same value in the A10 and A9 bits of their addresses, then when the Slave select address is sent from the Master, both the Master and Slave acknowledge it. When the Master sends out the read operation, both the Master and the Slave enter into Read mode and both of them transmit the data. The resultant data will be the ANDing of the two transmissions.

#### Work around

In all I<sup>2</sup>C devices, the addresses as well as bits A10 and A9 should be different.

#### Affected Silicon Revisions

A3	A4						
X	X						

**6. Module: I<sup>2</sup>C**

When the I<sup>2</sup>C module is operating in either Master or Slave mode, after the ACKSTAT bit is set when receiving a NACK, it may be cleared by the reception of a Start or Stop bit.

**Work around**

Store the value of the ACKSTAT bit immediately after receiving a NACK.

**Affected Silicon Revisions**

A3	A4						
X	X						

**7. Module: I<sup>2</sup>C**

In 10-bit Addressing mode, some address matches do not set the RBF flag or load the receive register I2CxRCV if the lower address byte matches the reserved addresses. In particular, these include all addresses with the form XX0000XXXX and XX1111XXXX, with the following exceptions:

- 001111000X
- 011111001X
- 101111010X
- 111111011X

**Work around**

Ensure that the lower address byte in 10-bit Addressing mode does not match any 7-bit reserved addresses.

**Affected Silicon Revisions**

A3	A4						
X	X						

**8. Module: I<sup>2</sup>C**

When the I<sup>2</sup>C module is configured as a 10-bit slave with an address of 0x102, the I2CxRCV register content for the lower address byte is 0x01 rather than 0x02; however, the module acknowledges both address bytes.

**Work around**

None.

**Affected Silicon Revisions**

A3	A4						
X	X						

**9. Module: SPI**

In framed SPI mode, when the FRMDLY bit (SPIxCON2<1>) is cleared and the SMP bit (SPIxCON1<9>) is cleared, frame sync pulses do not get generated.

**Work around**

None.

**Affected Silicon Revisions**

A3	A4						
X	X						

**10. Module: Internal Voltage Regulator**

When the VREGS bit (RCON<8>) is set to a logic '0', the device may Reset and a higher sleep current may be observed.

**Work around**

Ensure VREGS bit (RCON<8>) is set to a logic '1' for device Sleep mode operation.

**Affected Silicon Revisions**

A3	A4						
X	X						

**11. Module: PSV Operations**

An address error trap occurs in certain addressing modes when accessing the first four bytes of an PSV page. This only occurs when using the following addressing modes:

- MOV.D
- Register Indirect Addressing (word or byte mode) with pre/post-decrement

**Work around**

Do not perform PSV accesses to any of the first four bytes using the above addressing modes. For applications using the C language, MPLAB C30 version 3.11 or higher, provides the following command-line switch that implements a work around for the erratum.

```
-merrata=psv_trap
```

Refer to the `readme.txt` file in the MPLAB C30 v3.11 tool suite for further details.

**Affected Silicon Revisions**

A3	A4						
X	X						

**12. Module: CPU**

The EXCH instruction does not execute correctly.

**Work around**

If writing source code in assembly, the recommended work around is to replace:

```
EXCH Wsource, Wdestination
```

with:

```
PUSH Wdestination
```

```
MOV Wsource, Wdestination
```

```
POP Wsource
```

If using the MPLAB C30 C compiler, specify the compiler option: `-merrata=exch` (*Project > Build Options > Projects > MPLAB C30 > Use Alternate Settings*).

**Affected Silicon Revisions**

A3	A4						
X	X						

**13. Module: SPI**

Writing to the SPIxBUF register as soon as the TBF bit is cleared will cause the SPI module to ignore the written data. Applications which use SPI with DMA will not be affected by this erratum.

**Work around**

After the TBF bit is cleared, wait for a minimum duration of one SPI Clock before writing to the SPIxBUF register.

Alternatively, do one of the following:

1. Poll the RBF bit and wait for it to get set before writing to the SPIxBUF register.
2. Poll the SPI Interrupt flag and wait for it to get set before writing to the SPIxBUF register.
3. Use an SPI Interrupt Service Routine.
4. Use DMA.

**Affected Silicon Revisions**

A3	A4						
X	X						

**14. Module: ECAN**

ECAN module may not transmit Buffer 0 data if Buffer 1 data is queued for transmission first. This problem is specific to transmit Buffers 0 and 1 only.

**Work around**

The issue can be fixed by setting reserved bit 11 in CiCTRL1 register to 1. Note that the module reset value for this bit is zero.

**Affected Silicon Revisions**

A3	A4						
X	X						

**15. Module: UART**

The UART module will not generate consecutive break characters. Trying to perform a back-to-back Break character transmission will cause the UART module to transmit the dummy character used to generate the first Break character instead of transmitting the second Break character. Break characters are generated correctly if they are followed by non-Break character transmission.

**Work around**

None.

**Affected Silicon Revisions**

A3	A4						
X	X						

**16. Module: I/O**

While device is being programmed via PGECx/ PGEDx pin pair, device pin with SDO1 functionality may start toggling.

**Work around**

None.

**Affected Silicon Revisions**

A3	A4						
X	X						

**17. Module: ADC**

If the ADC module is in an enabled state when the device enters Sleep mode as a result of executing a `PWRSVAV #0` instruction, the device power-down current (IPD) may exceed the specifications listed in the device data sheet. This may happen even if the ADC module is disabled by clearing the ADON bit prior to entering Sleep mode.

**Work around 1:**

In order to remain within the IPD specifications listed in the device data sheet, the user software must completely disable the ADC module by setting the ADC Module Disable bit in the corresponding Peripheral Module Disable register (PMDx), prior to executing a `PWRSVAV #0` instruction.

**Note:** The ADC module must be reinitialized by the user application before resuming ADC operation.

**Work around 2:**

If the ADC module was previously initialized and enabled, before entering Sleep, execute the lines of code provided in [Example 1](#).

**Note:** Unlike **Work around 1**, the user application does not need to reinitialize the ADC module; however, it is necessary to re-enable the ADC module by setting the ADON bit after waking from Sleep.

**Affected Silicon Revisions**

A3	A4						
X	X						

**18. Module: All**

The affected silicon revisions listed below are not warranted for operation at 150°C.

**Work around**

Only use the affected revisions of silicon for Hi-Temp operating range from -40°C to +140°C.

**Affected Silicon Revisions**

A3	A4						
X	X						

**EXAMPLE 1:**

```
AD1CON1bits.ADON = 0;           //Disable the ADC module
__asm__ volatile ("REPEAT #50"); //Wait 50 Tcy
__asm__ volatile ("NOP");       //Repeat NOP 51 times
Sleep();                        // Execute PWRSVAV #0 and go to Sleep
```

**Data Sheet Clarifications**

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS70593B):

**Note:** Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

**1. Module: DC Characteristics: I/O Pin Input Specifications**

The maximum value for parameter DI19 ( $V_{IL}$  specifications for SDAx and SCLx pins) was stated incorrectly in Table 25-9 of the current device data sheet. Also, parameters DI28 and DI29 ( $V_{IH}$  specifications for SDAx and SCLx pins) were not stated. The correct values are shown in bold type in [Table 3](#).

**TABLE 3: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS**

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
DI18	V <sub>IL</sub>	Input Low Voltage <b>SDAx, SCLx</b>	V <sub>SS</sub>	—	0.3 V <sub>DD</sub>	V	SMBus disabled
DI19		<b>SDAx, SCLx</b>	V <sub>SS</sub>	—	<b>0.8</b>	V	SMBus enabled
DI28	V <sub>IH</sub>	Input High Voltage <b>SDAx, SCLx</b>	<b>0.7 V<sub>DD</sub></b>	—	<b>5.5</b>	V	<b>SMBus disabled</b>
DI29		<b>SDAx, SCLx</b>	<b>2.1</b>	—	<b>5.5</b>	V	<b>SMBus enabled</b>



## **APPENDIX A: REVISION HISTORY**

### Rev A Document (4/2009)

Initial release of this document; issued for revision A3 and A4 silicon.

Includes silicon issues 1 ([ECAN](#)), 2-4 ([UART](#)), 5-8 ([I<sup>2</sup>C](#)), 9 ([SPI](#)), 10 ([Internal Voltage Regulator](#)), 11 ([PSV Operations](#)), 12 ([CPU](#)), 13 ([SPI](#)) and 14 ([ECAN](#)).

### Rev B Document (8/2009)

Added silicon issue 15 ([UART](#)) and 16 ([I/O](#)).

### Rev C Document (5/2010)

Updated silicon issue 12 ([CPU](#)).

Added silicon issue 17 ([ADC](#)) and data sheet clarification 1 ([DC Characteristics: I/O Pin Input Specifications](#)).

### Rev D Document (10/2010)

Updated the work around in silicon issue 17 ([ADC](#)).

Added silicon issue 18 ([All](#)).

**NOTES:**

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**Note the following details of the code protection feature on Microchip devices:**

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